

NLSX3373

2-Bit 20 Mb/s Dual-Supply Level Translator

The NLSX3373 is a 2-bit configurable dual-supply bidirectional auto sensing translator that does not require a directional control pin. The V_{CC} I/O and V_L I/O ports are designed to track two different power supply rails, V_{CC} and V_L respectively. The V_{CC} supply rail is configurable from 1.65 V to 4.5 V while V_L supply rail is configurable to 1.2 V to 4.1 V. This allows lower voltage logic signals on the V_L side to be translated into higher voltage logic signals on the V_{CC} side, and vice-versa.

The NLSX3373 translator has open-drain outputs with integrated 10 k Ω pullup resistors on the I/O lines. The integrated pullup resistors are used to pullup the I/O lines to either V_L or V_{CC} . The NLSX3373 is an excellent match for open-drain applications such as the I²C communication bus.

Features

- Wide High-Side V_{CC} Operating Range: 1.65 V to 4.5 V
Wide Low-Side V_L Operating Range: 1.2 V to 4.1 V
- High-Speed with 20 Mb/s Guaranteed Data Rate for $V_L > 2.5$ V
- Low Bit-to-Bit Skew
- Enable Input and I/O Lines have Overvoltage Tolerant (OVT) to 4.5 V
- Nonpreferential Powerup Sequencing
- Integrated 10 k Ω Pullup Resistors
- Small Space Saving Package – 1.8 x 1.2 x 0.5 mm UDFN8
- This is a Pb-Free Device

Typical Applications

- I²C, SMBus, PMBus
- Low Voltage ASIC Level Translation
- Mobile Phones, PDAs, Cameras

Important Information

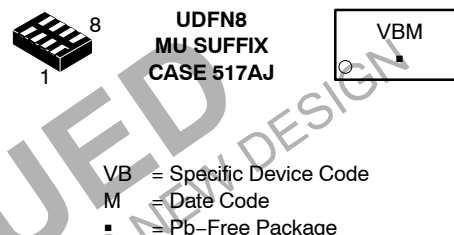
- ESD Protection for Power, Enable and I/O Pins:
Human Body Model (HBM): ± 7.5 kV
Machine Model (MM): 400 V



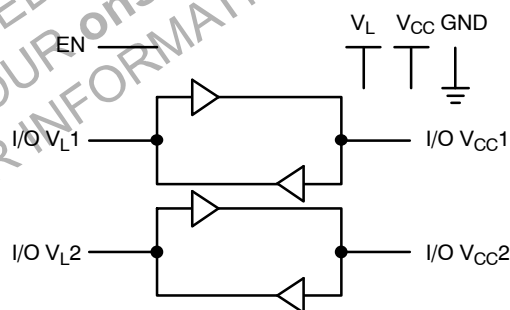
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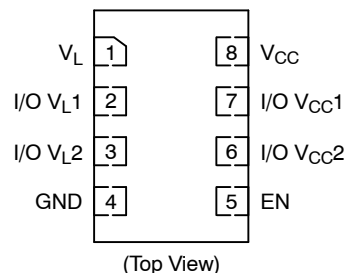
MARKING DIAGRAM



LOGIC DIAGRAM



PIN ASSIGNMENT



ORDERING INFORMATION

Device	Package	Shipping†
NLSX3373MUTAG	UDFN8 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

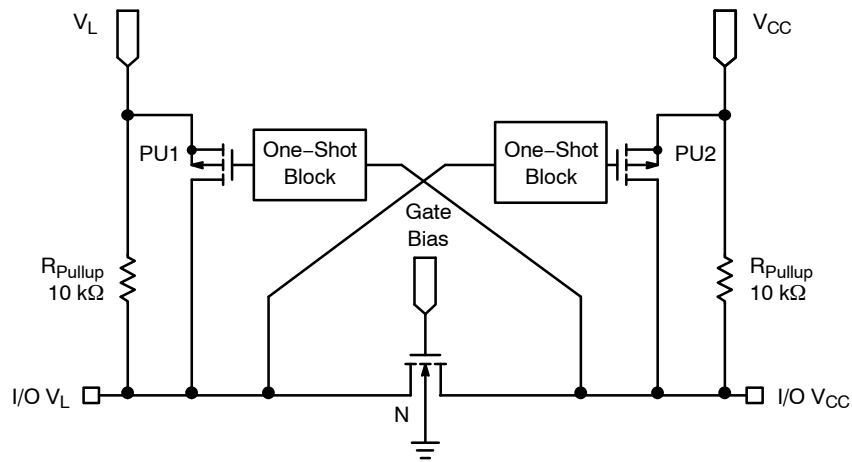


Figure 1. Block Diagram (1 I/O Line)

PIN ASSIGNMENT

Pins	Description
V _{CC}	V _{CC} Input Voltage
V _L	V _L Input Voltage
GND	Ground
EN	Output Enable
I/O V _{CCn}	V _{CC} I/O Port, Referenced to V _{CC}
I/O V _{Ln}	V _L I/O Port, Referenced to V _L

FUNCTION TABLE

EN	Operating Mode
L	Hi-Z
H	I/O Buses Connected

MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Unit
V _{CC}	High-side DC Supply Voltage	−0.3 to +7.0		V
V _L	High-side DC Supply Voltage	−0.3 to +7.0		V
I/O V _{CC}	V _{CC} –Referenced DC Input/Output Voltage	−0.3 to (V _{CC} + 0.3)		V
I/O V _L	V _L –Referenced DC Input/Output Voltage	−0.3 to (V _L + 0.3)		V
V _{EN}	Enable Control Pin DC Input Voltage	−0.3 to +7.0		V
I _{I/O_SC}	Short-Circuit Duration (I/O V _L and I/O V _{CC} to GND)	40	Continuous	mA
T _{STG}	Storage Temperature	−65 to +150		°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	High-side Positive DC Supply Voltage	1.65	4.5	V
V _L	High-side Positive DC Supply Voltage	1.2	4.1	V
V _{EN}	Enable Control Pin Voltage	GND	4.5	V
V _{IO}	Enable Control Pin Voltage	GND	4.5	V
T _A	Operating Temperature Range	−40	+85	°C

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DC ELECTRICAL CHARACTERISTICS ($V_{CC} = 1.65 \text{ V}$ to 4.5 V and $V_L = 1.2 \text{ V}$ to 4.1 V , unless otherwise specified)

Symbol	Parameter	Test Conditions	-40°C to +85°C			Unit
			Min	Typ (Notes 1, 2)	Max	
V_{IHC}	I/O V_{CC} Input HIGH Voltage		$V_{CC} - 0.4$	–	–	V
V_{ILC}	I/O V_{CC} Input LOW Voltage		–	–	0.15	V
V_{IHL}	I/O V_L Input HIGH Voltage		$V_L - 0.2$	–	–	V
V_{ILL}	I/O V_L Input LOW Voltage		–	–	0.15	V
V_{IH}	Control Pin Input HIGH Voltage		$V_L - 0.2$	–	–	V
V_{IL}	Control Pin Input LOW Voltage		–	–	0.15	V
V_{OHC}	I/O V_{CC} Output HIGH Voltage	I/O V_{CC} Source Current = 20 μA	$2/3 * V_{CC}$	–	–	V
V_{OLC}	I/O V_{CC} Output LOW Voltage	I/O V_{CC} Sink Current = 20 μA	–	–	$1/3 * V_{CC}$	V
V_{OHL}	I/O V_L Output HIGH Voltage	I/O V_L Source Current = 20 μA	$2/3 * V_L$	–	–	V
V_{OLL}	I/O V_L Output LOW Voltage	I/O V_L Sink Current = 20 μA	–	–	$1/3 * V_L$	V
I_{QVCC}	V_{CC} Supply Current	I/O V_{CC} and I/O V_L Unconnected, $V_{EN} = V_L$	–	45	75	μA
I_{QVL}	V_L Supply Current	I/O V_{CC} and I/O V_L Unconnected, $V_{EN} = V_L$	–	1.0	5.0	μA
I_{TS-VCC}	V_{CC} Tristate Output Mode Supply Current	I/O V_{CC} and I/O V_L Unconnected, $V_{EN} = \text{GND}$	–	0.1	2.5	μA
I_{TS-VL}	V_L Tristate Output Mode Supply Current	I/O V_{CC} and I/O V_L Unconnected, $V_{EN} = \text{GND}$	–	0.1	2.5	μA
I_{OZ}	I/O Tristate Output Mode Leakage Current	$T_A = +25^\circ\text{C}$	–	–	2.5	μA
R_{PU}	Pullup Resistor I/O V_L and V_{CC}	$T_A = +25^\circ\text{C}$	–	10	–	$\text{k}\Omega$

1. Typical values are for $V_{CC} = +2.8 \text{ V}$, $V_L = +1.8 \text{ V}$ and $T_A = +25^\circ\text{C}$.
2. All units are production tested at $T_A = +25^\circ\text{C}$. Limits over the operating temperature range are guaranteed by design.

TIMING CHARACTERISTICS – RAIL-TO-RAIL DRIVING CONFIGURATIONS(I/O test circuit of Figures 2 and 3, $C_{LOAD} = 15 \text{ pF}$, driver output impedance $\leq 50 \Omega$, $R_{LOAD} = 1 \text{ M}\Omega$)

Symbol	Parameter	Test Conditions	–40°C to +85°C (Notes 3 and 4)			Unit
			Min	Typ	Max	
+1.2 ≤ V _L ≤ V _{CC} ≤ +4.5 V						
t _{RVCC}	I/O V _{CC} Risetime				25	ns
t _{FVCC}	I/O V _{CC} Falltime				37	ns
t _{RVL}	I/O V _L Risetime				30	ns
t _{FVL}	I/O V _L Falltime				30	ns
t _{PDVL-VCC}	Propagation Delay (Driving I/O V _L)				30	ns
t _{PDVCC-VL}	Propagation Delay (Driving I/O V _{CC})				30	ns
t _{PPSKEW}	Part-to-Part Skew				20	nS
	Maximum Data Rate		8			Mb/s

+1.2 ≤ V_L ≤ V_{CC} ≤ +3.3 V

t_{RVCC}	I/O V_{CC} Risettime				25	ns
t_{FVCC}	I/O V_{CC} Falltime				30	ns
t_{RVL}	I/O V_L Risettime				30	ns
t_{FVL}	I/O V_L Falltime				30	ns
$t_{PDVL-VCC}$	Propagation Delay (Driving I/O V_L)				20	ns
$t_{PDVCC-VL}$	Propagation Delay (Driving I/O V_{CC})				20	ns
t_{PPSKEW}	Part-to-Part Skew				10	nS
	Maximum Data Rate		10			Mb/s

+1.8 ≤ V_L ≤ V_{CC} ≤ +2.5 V

t_{RVCC}	I/O V_{CC} Risettime				15	ns
t_{FVCC}	I/O V_{CC} Falltime				15	ns
t_{RVL}	I/O V_L Risettime				15	ns
t_{FVL}	I/O V_L Falltime				15	ns
$t_{PDVL-VCC}$	Propagation Delay (Driving I/O V_L)				15	ns
$t_{PDVCC-VL}$	Propagation Delay (Driving I/O V_{CC})				15	ns
t_{PPSKEW}	Part-to-Part Skew				10	nS
	Maximum Data Rate		16			Mb/s

+2.5 ≤ V_L ≤ V_{CC} ≤ +3.3 V

t_{RVCC}	I/O V_{CC} Risettime				15	ns
t_{FVCC}	I/O V_{CC} Falltime				15	ns
t_{RVL}	I/O V_L Risettime				15	ns
t_{FVL}	I/O V_L Falltime				15	ns
$t_{PDVL-VCC}$	Propagation Delay (Driving I/O V_L)				15	ns
$t_{PDVCC-VL}$	Propagation Delay (Driving I/O V_{CC})				15	ns
t_{PPSKEW}	Part-to-Part Skew				10	nS
	Maximum Data Rate		20			Mb/s

3. Typical values are for $V_{CC} = +3.3 \text{ V}$, $V_L = +1.8 \text{ V}$ and $T_A = +25^\circ\text{C}$.4. All units are production tested at $T_A = +25^\circ\text{C}$. Limits over the operating temperature range are guaranteed by design.

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TIMING CHARACTERISTICS – OPEN DRAIN DRIVING CONFIGURATIONS

(I/O test circuit of Figures 4 and 5, $C_{LOAD} = 15 \text{ pF}$, driver output impedance $\leq 50 \Omega$, $R_{LOAD} = 1 \text{ M}\Omega$)

Symbol	Parameter	Test Conditions	–40°C to +85°C (Notes 5 and 6)			Unit
			Min	Typ	Max	
+1.2 ≤ V _L ≤ V _{CC} ≤ +4.5 V						
t _{RVCC}	I/O V _{CC} Risettime				400	ns
t _{FVCC}	I/O V _{CC} Falltime				50	ns
t _{RVL}	I/O V _L Risettime				400	ns
t _{FVL}	I/O V _L Falltime				60	ns
t _{PDVL-VCC}	Propagation Delay (Driving I/O V _L)				1000	ns
t _{PDVCC-VL}	Propagation Delay (Driving I/O V _{CC})				1000	ns
t _{PPSKEW}	Part-to-Part Skew				50	nS
MDR	Maximum Data Rate		2			Mb/s

5. Typical values are for V_{CC} = +3.3 V, V_L = +1.8 V and T_A = +25°C.

6. All units are production tested at T_A = +25°C. Limits over the operating temperature range are guaranteed by design. Limits over the operating temperature range are guaranteed by design.

DISCONTINUED
THIS DEVICE IS NOT RECOMMENDED FOR NEW DESIGN
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TEST SETUPS

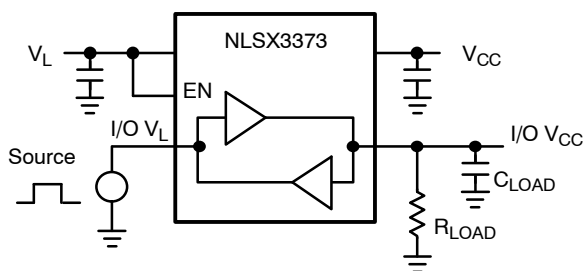


Figure 2. Rail-to-Rail Driving I/O V_L

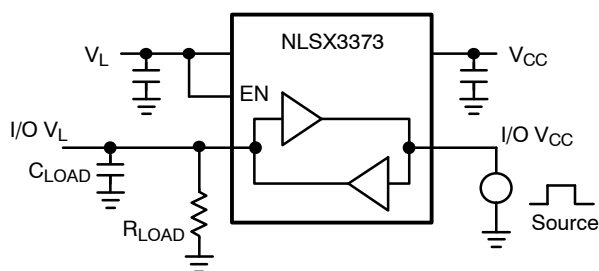


Figure 3. Rail-to-Rail Driving I/O V_{CC}

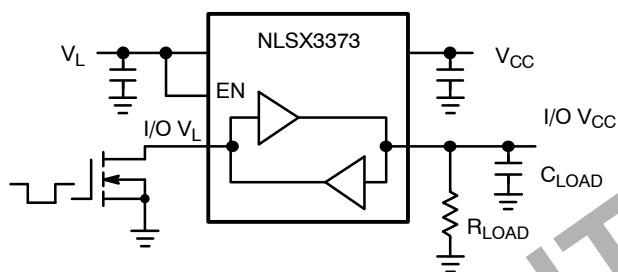


Figure 4. Open-Drain Driving I/O V_L

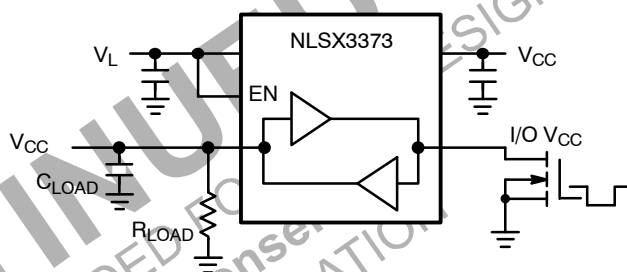


Figure 5. Open-Drain Driving I/O V_{CC}

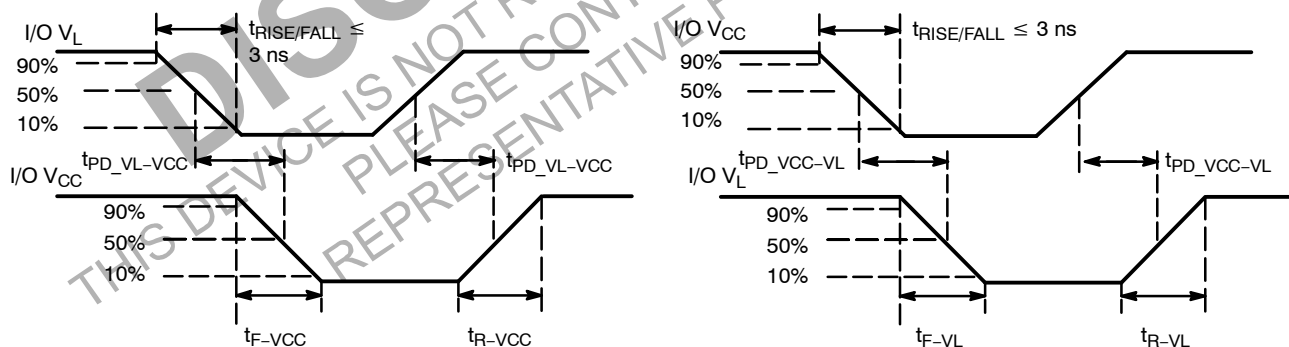
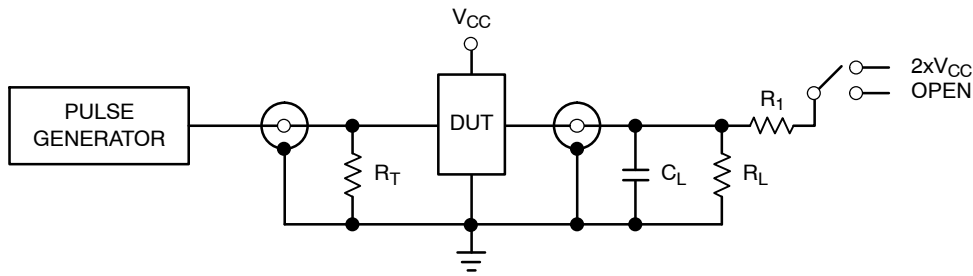


Figure 6. Definition of Timing Specification Parameters



Test	Switch
t_{PZH} , t_{PHZ}	Open
t_{PZL} , t_{PLZ}	$2 \times V_{CC}$

$C_L = 15 \text{ pF}$ or equivalent (Includes jig and probe capacitance)
 $R_L = R_1 = 50 \text{ k}\Omega$ or equivalent
 $R_T = Z_{OUT}$ of pulse generator (typically 50Ω)

Figure 7. Test Circuit for Enable/Disable Time Measurement

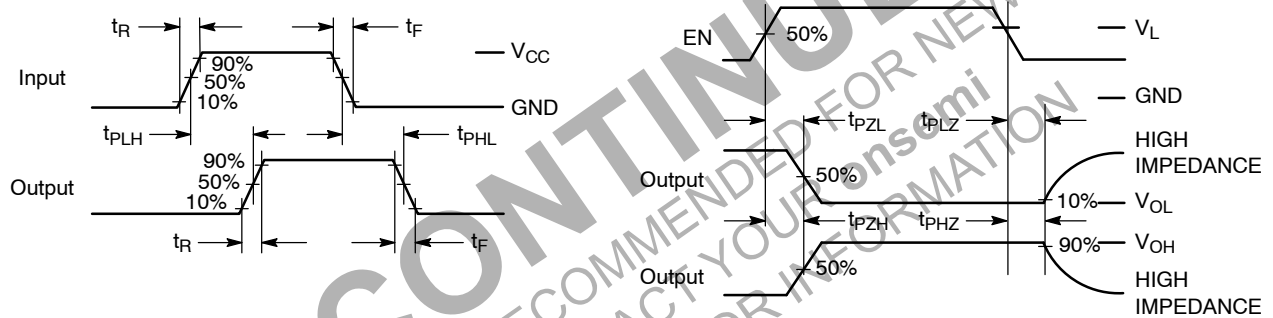


Figure 8. Timing Definitions for Propagation Delays and Enable/Disable Measurement

APPLICATIONS INFORMATION

Level Translator Architecture

The NLSX3373 auto sense translator provides bi-directional voltage level shifting to transfer data in multiple supply voltage systems. This device has two supply voltages, V_L and V_{CC} , which set the logic levels on the input and output sides of the translator. When used to transfer data from the V_L to the V_{CC} ports, input signals referenced to the V_L supply are translated to output signals with a logic level matched to V_{CC} . In a similar manner, the V_{CC} to V_L translation shifts input signals with a logic level compatible to V_{CC} to an output signal matched to V_L .

The NLSX3373 consists of two bi-directional channels that independently determine the direction of the data flow without requiring a directional pin. The one-shot circuits are used to detect the rising or falling input signals. In addition, the one shots decrease the rise and fall time of the output signal for high-to-low and low-to-high transitions.

Each input/output channel has an internal 10 k Ω pull. The magnitude of the pullup resistors can be reduced by connecting external resistors in parallel to the internal 10 k Ω resistors.

Input Driver Requirements

The rise (t_R) and fall (t_F) timing parameters of the open drain outputs depend on the magnitude of the pull-up resistors. In addition, the propagation times (t_{PD}), skew (t_{PSKEW}) and maximum data rate depend on the impedance of the device that is connected to the translator. The timing parameters listed in the data sheet assume that the output impedance of the drivers connected to the translator is less than 50 k Ω .

Enable Input (EN)

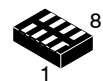
The NLSX3373 has an Enable pin (EN) that provides tri-state operation at the I/O pins. Driving the Enable pin to a low logic level minimizes the power consumption of the device and drives the I/O V_{CC} and I/O V_L pins to a high impedance state. Normal translation operation occurs when the EN pin is equal to a logic high signal. The EN pin is referenced to the V_L supply and has Overvoltage Tolerant (OVT) protection.

Power Supply Guidelines

During normal operation, supply voltage V_L should be less than or equal to V_{CC} . The sequencing of the power supplies will not damage the device during the power up operation.

The enable pin should be used to enter the low current tri-state mode, rather than setting either the V_L or V_{CC} supplies to 0 V. The NLSX3373 will not be damaged if either V_L or V_{CC} is equal to 0 V while the other supply voltage is at a nominal operating value; however, the operation of the translator cannot be guaranteed during single supply operation.

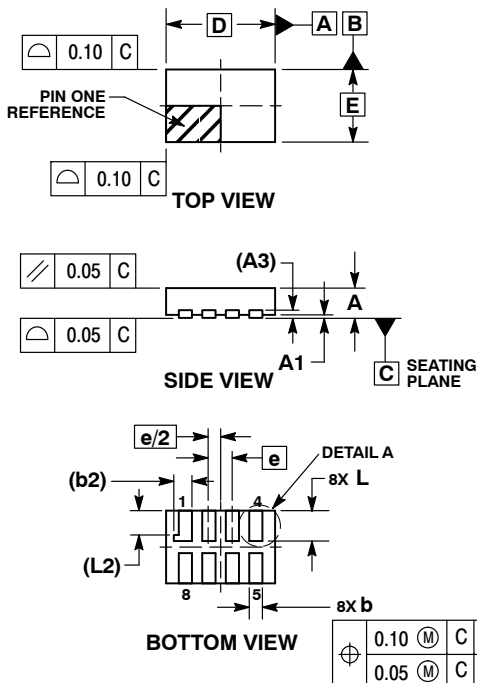
For optimal performance, 0.01 μ F to 0.1 μ F decoupling capacitors should be used on the V_L and V_{CC} power supply pins. Ceramic capacitors are a good design choice to filter and bypass any noise signals on the voltage lines to the ground plane of the PCB. The noise immunity will be maximized by placing the capacitors as close as possible to the supply and ground pins, along with minimizing the PCB connection traces.



SCALE 4:1

UDFN8 1.8x1.2, 0.4P
CASE 517AJ
ISSUE O

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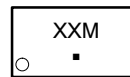


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.
4. MOLD FLASH ALLOWED ON TERMINALS ALONG EDGE OF PACKAGE. FLASH MAY NOT EXCEED 0.03 ONTO BOTTOM SURFACE OF TERMINALS.
5. DETAIL A SHOWS OPTIONAL CONSTRUCTION FOR TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.127 REF	
b	0.15	0.25
b2	0.30 REF	
D	1.80 BSC	
E	1.20 BSC	
e	0.40 BSC	
L	0.45	0.55
L1	0.00	0.03
L2	0.40 REF	

GENERIC
MARKING DIAGRAM*



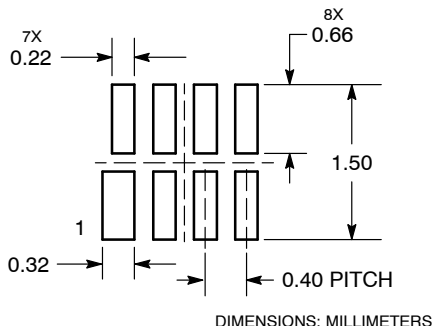
XX = Specific Device Code

M = Date Code

▪ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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